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Features

- 3A Peak Output Current
- Wide Operating Voltage Range: 4.5V to 35V
- -40°C to +125°C Operating Temperature Range
- Latch-up Protected to 3A
- Fast Rise and Fall Times
- Low Power Consumption

Applications

- MOSFET Driver
- Switching Power Supplies
- Motor Controls
- DC to DC Converters
- Pulse Transformer Driver

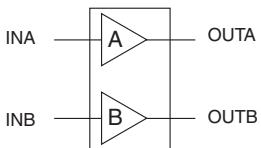
Description

The IX4424G is a dual, non-inverting, high-speed, low-side gate driver. Each of the two outputs can source and sink 3A of peak current with rise and fall times of less than 10ns. The inputs of each driver are TTL and CMOS compatible, and are virtually immune to latch-up. Low propagation delay times and fast, matched rise and fall times make the IX4424G ideal for high-frequency and high-power applications.

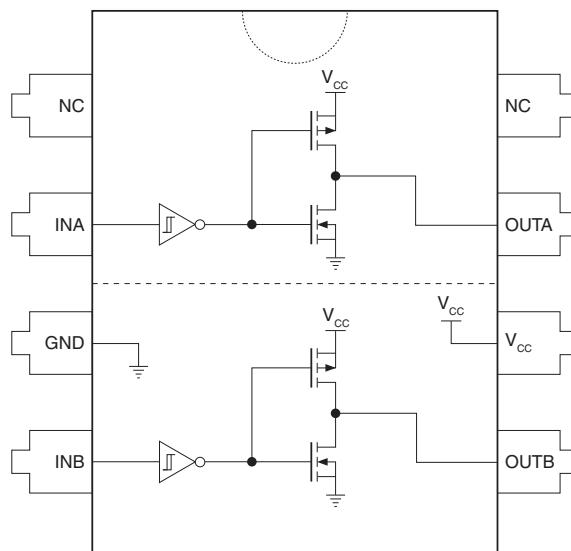
The IX4424G is configured as a dual non-inverting driver that is available in a standard 8-pin DIP package.



Ordering Information

Logic Configuration	Part Number	Package Type	Packing Method	Quantity
	IX4424G	8-Pin DIP	Tube	50

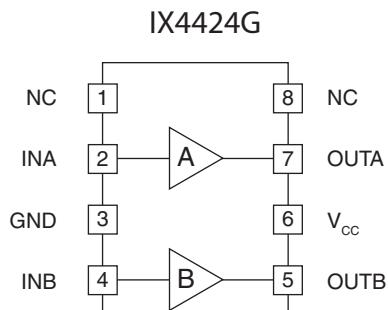
IX4424G Diagram



1. Specifications	3
1.1 Pin Configuration	3
1.2 Pin Definitions	3
1.3 Absolute Maximum Ratings	3
1.4 Recommended Operating Conditions	3
1.5 Electrical Characteristics: $T_A = 25^\circ\text{C}$	4
1.6 Electrical Characteristics: $T_A = - 40^\circ\text{C}$ to $+125^\circ\text{C}$	4
1.7 Thermal Characteristics	4
2. IX4424G Performance	5
2.1 Timing Diagram	5
2.2 Characteristics Test Diagram	5
3. Block Diagram & Truth Table	5
3.1 IX4424G	5
4. Typical Performance Characteristics	6
5. Manufacturing Information	9
5.1 Moisture Sensitivity	9
5.2 ESD Sensitivity	9
5.3 Soldering Profile	9
5.4 Mechanical Dimensions	10

1 Specifications

1.1 Pin Configuration



1.2 Pin Definitions

Pin Name	Description
INA	Channel A Logic Input
INB	Channel B Logic Input
OUTA	Channel A Output - Sources or sinks current to turn-on or turn-off a discrete MOSFET or IGBT
OUTB	Channel B Output - Sources or sinks current to turn on or turn off a discrete MOSFET or IGBT
V _{CC}	Supply Voltage - Provides power to the device
GND	Ground - Common ground reference for the device
NC	No Connection

1.3 Absolute Maximum Ratings

Parameter	Symbol	Minimum	Maximum	Units
Supply Voltage	V _{CC}	-0.3	35	V
Input Voltage	V _{IN}	-5.0	V _{CC} +0.3	V
Output Current	I _{OUT}	-	±3	A
Junction Temperature	T _J	-55	+150	°C
Storage Temperature	T _{STG}	-65	+150	°C

Unless otherwise specified, absolute maximum electrical ratings are at 25°C

Absolute maximum ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

1.4 Recommended Operating Conditions

Parameter	Symbol	Minimum	Maximum	Units
Supply Voltage	V _{CC}	4.5	30	V
Operating Temperature Range	T _A	-40	+125	°C

1.5 Electrical Characteristics: $T_A = 25^\circ\text{C}$

Test Conditions: $4.5\text{V} \leq V_{CC} \leq 18\text{V}$.

Parameter	Conditions	Symbol	Minimum	Typical	Maximum	Units
Input Voltage, High	-	V_{IH}	3	-	-	V
Input Voltage, Low	-	V_{IL}	-	-	0.8	
Input Current	$0\text{V} \leq V_{IN} \leq V_{CC}$	I_{IN}	-	-	± 10	μA
Output Voltage, High	-	V_{OH}	$V_{CC}-0.025$	-	-	
Output Voltage, Low	-	V_{OL}	-	-	0.025	V
Output Resistance, High State	$V_{CC}=18\text{V}, I_{OUT}=-100\text{mA}$	R_{OH}	-	2.5	4	Ω
Output Resistance, Low State	$V_{CC}=18\text{V}, I_{OUT}=100\text{mA}$	R_{OL}	-	1.5	3	
Rise Time	$V_{CC}=18\text{V}, C_{LOAD}=1000\text{pF}$	t_R	-	18	35	ns
Fall Time	$V_{CC}=18\text{V}, C_{LOAD}=1000\text{pF}$	t_F	-	18	35	
On-Time Propagation Delay	$V_{CC}=18\text{V}, C_{LOAD}=1000\text{pF}$	t_{on}	-	35	75	
Off-Time Propagation Delay	$V_{CC}=18\text{V}, C_{LOAD}=1000\text{pF}$	t_{off}	-	38	75	
Power Supply Current	$V_{INA}=V_{INB}=3.5\text{V}$	I_{CC}	-	1	3	mA
	$V_{INA}=V_{INB}=0\text{V}$		-	0.001	0.01	

1.6 Electrical Characteristics: $T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$

Test Conditions: $4.5\text{V} \leq V_{CC} \leq 18\text{V}$.

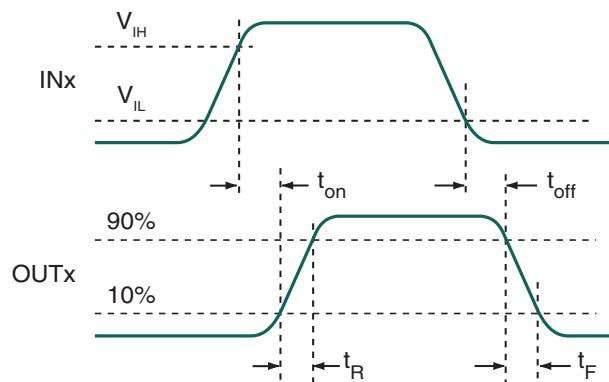
Parameter	Conditions	Symbol	Minimum	Maximum	Units
Input Voltage, High	-	V_{IH}	3.3	-	V
Input Voltage, Low	-	V_{IL}	-	0.65	
Input Current	$0\text{V} \leq V_{IN} \leq V_{CC}$	I_{IN}	-	± 10	μA
Output Voltage, High	-	V_{OH}	$V_{CC}-0.025$	-	
Output Voltage, Low	-	V_{OL}	-	0.025	V
Output Resistance, High State	$V_{CC}=18\text{V}, I_{OUT}=-100\text{mA}$	R_{OH}	-	6	Ω
Output Resistance, Low State	$V_{CC}=18\text{V}, I_{OUT}=100\text{mA}$	R_{OL}	-	5	
Rise Time	$V_{CC}=18\text{V}, C_{LOAD}=1000\text{pF}$	t_R	-	60	ns
Fall Time	$V_{CC}=18\text{V}, C_{LOAD}=1000\text{pF}$	t_F	-	60	
On-Time Propagation Delay	$V_{CC}=18\text{V}, C_{LOAD}=1000\text{pF}$	t_{on}	-	100	
Off-Time Propagation Delay	$V_{CC}=18\text{V}, C_{LOAD}=1000\text{pF}$	t_{off}	-	100	
Power Supply Current	$V_{INA}=V_{INB}=3.5\text{V}$	I_{CC}	-	3.5	mA
	$V_{INA}=V_{INB}=0\text{V}$		-	0.15	

1.7 Thermal Characteristics

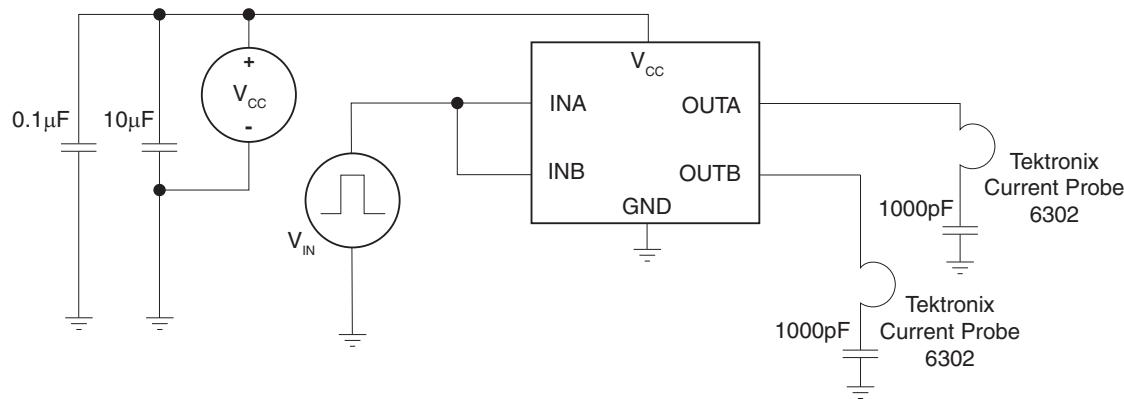
Package	Parameter	Symbol	Rating	Units
8-Pin DIP	Thermal Resistance, Junction-to-Ambient	θ_{JA}	125	$^\circ\text{C/W}$

2 IX4424G Performance

2.1 Timing Diagram

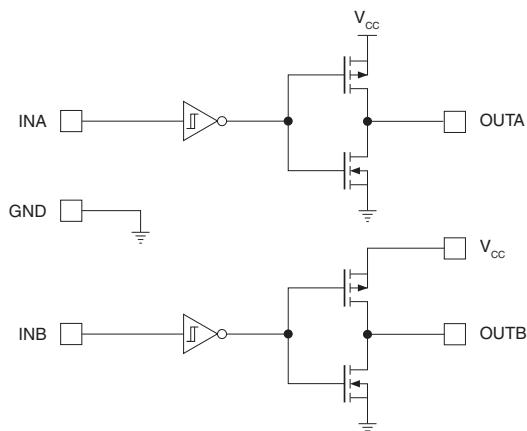


2.2 Characteristics Test Diagram



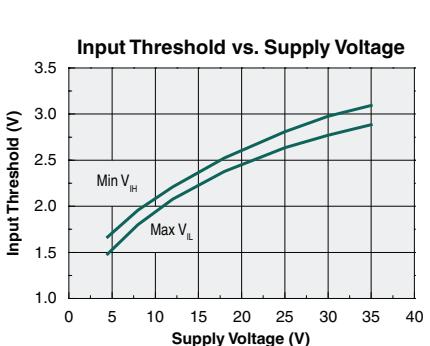
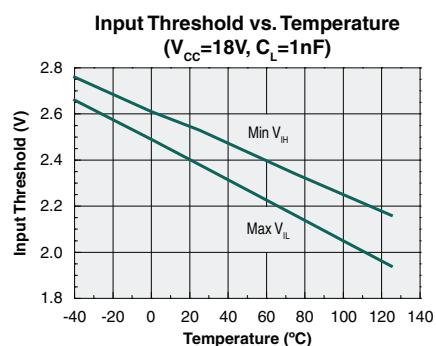
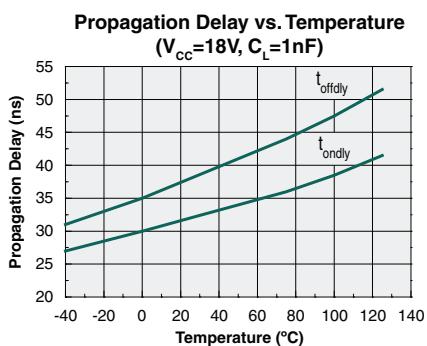
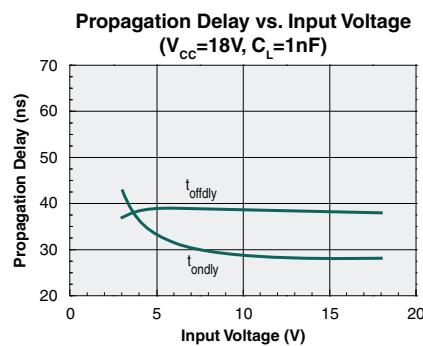
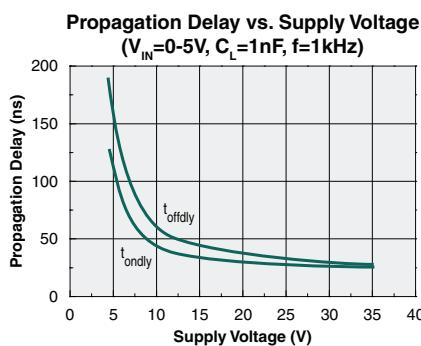
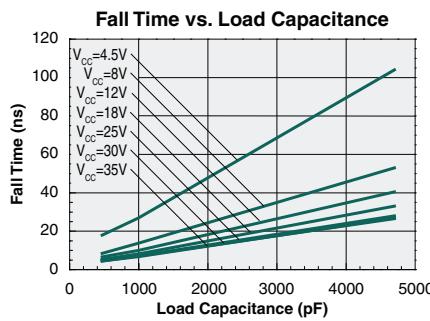
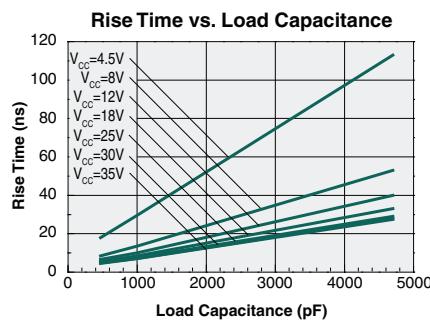
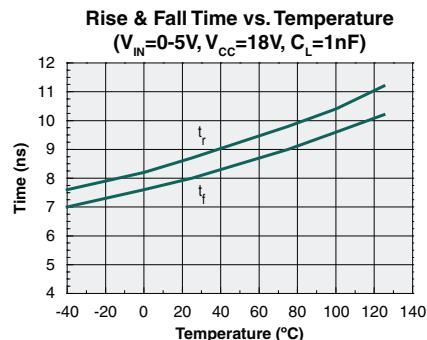
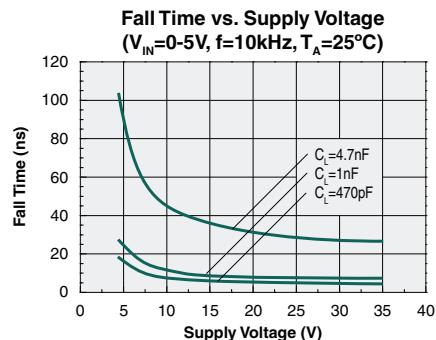
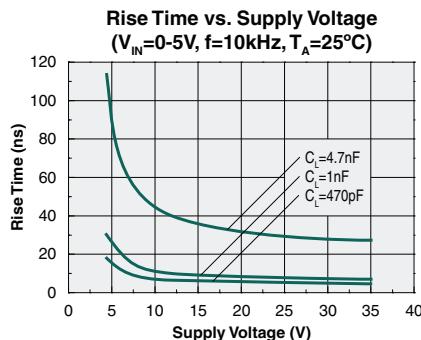
3 Block Diagram & Truth Table

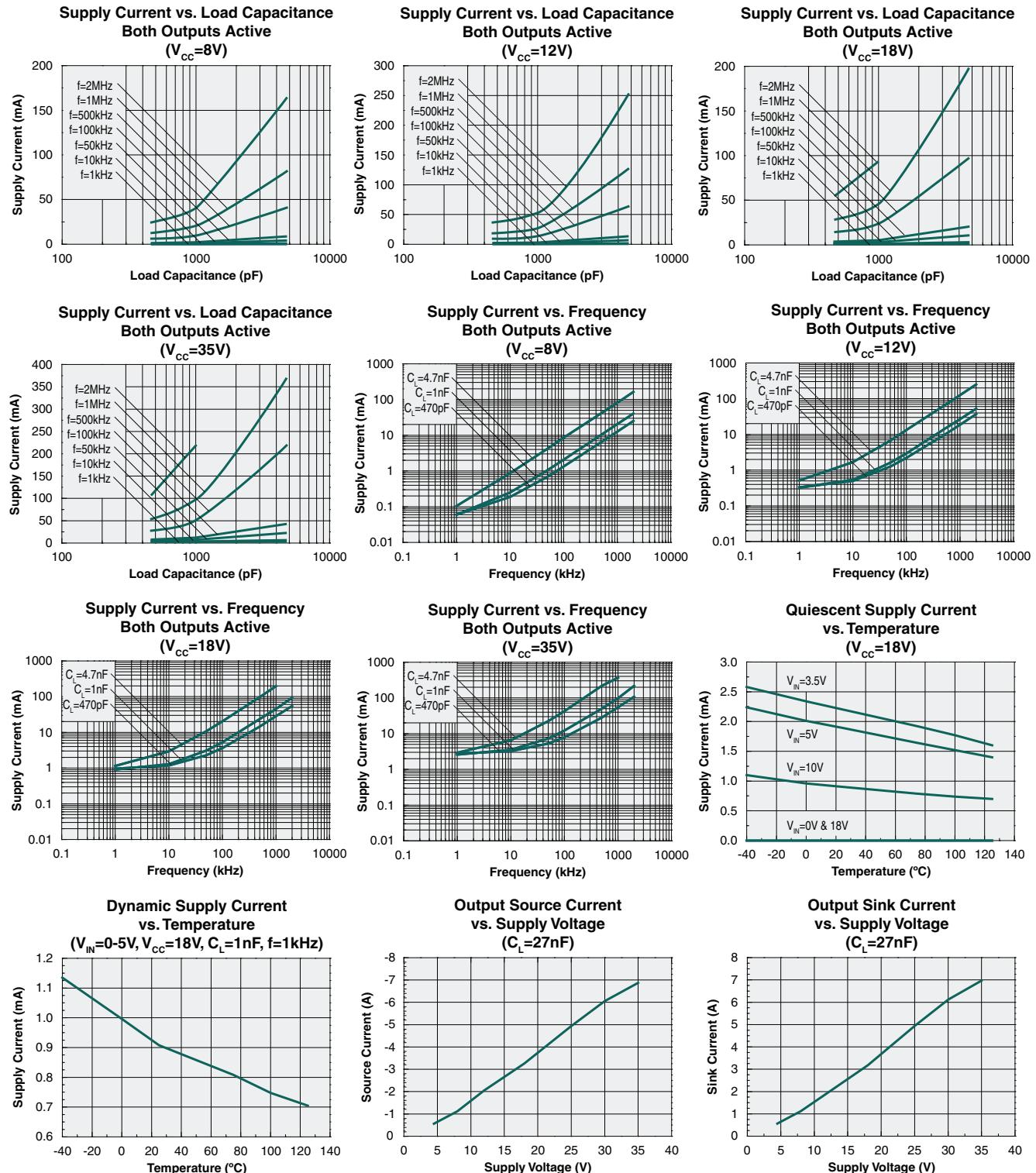
3.1 IX4424G

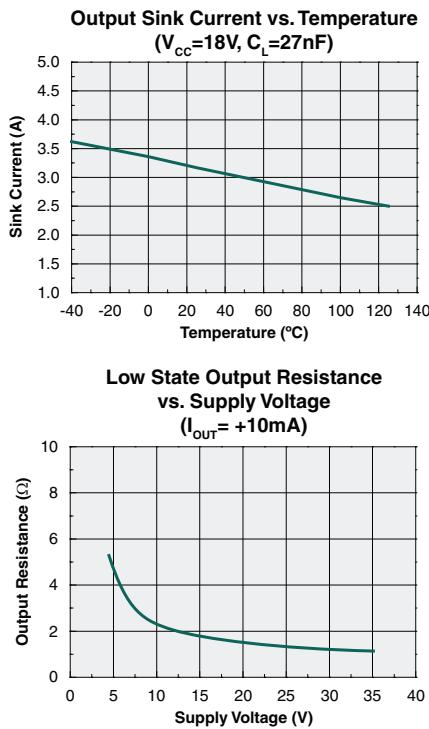
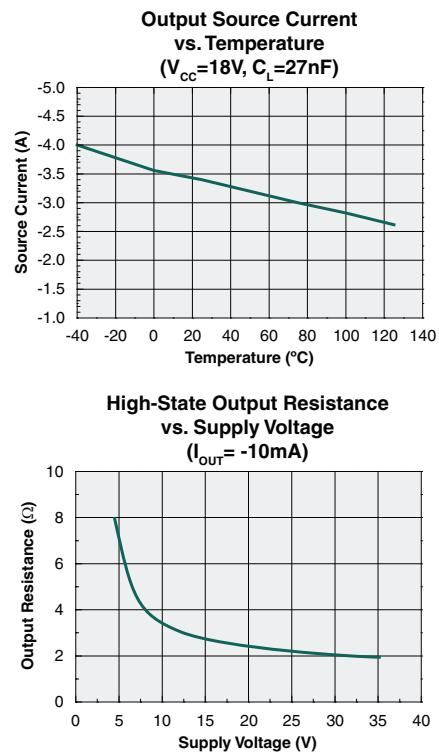


IN_x	OUT_x
0	0
1	1

4 Typical Performance Characteristics







5 Manufacturing Information

5.1 Moisture Sensitivity

 All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
IX4424G	MSL 1

5.2 ESD Sensitivity

 This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

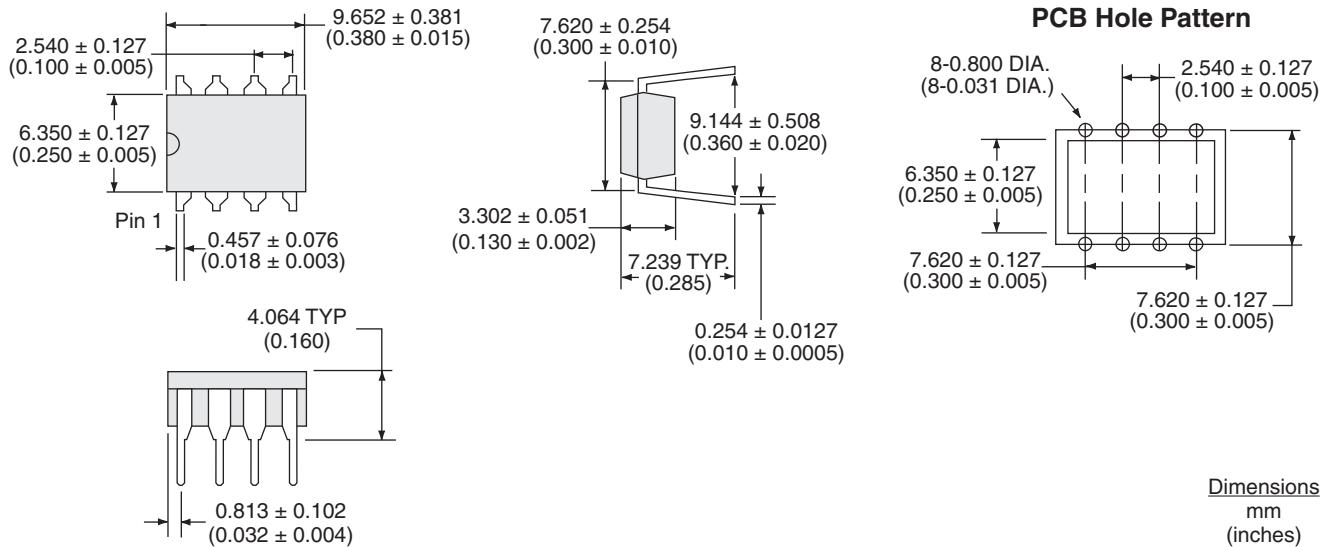
5.3 Soldering Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
IX4424G	250°C for 30 seconds



5.4 Mechanical Dimensions



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